



## Material Content Data Sheet



<b>Sales Product Name</b>		IPN70R2K0P7S		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001730324						
<b>Package</b>		PG-SOT223-3-1		<b>Weight*</b>		115.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.740	0.64	0.64	6388	6388
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		136	
	non noble metal	iron	7439-89-6	0.052	0.05		452	
	non noble metal	copper	7440-50-8	52.304	45.14	45.20	451407	451995
	non noble metal	copper	7440-50-8	0.157	0.14	0.14	1354	1354
wire	non noble metal	copper	7440-50-8	0.157	0.14	0.14	1354	1354
encapsulation	organic material	carbon black	1333-86-4	0.179	0.15		1549	
	plastics	epoxy resin	-	7.000	6.04		60412	
	inorganic material	silicondioxide	60676-86-0	52.649	45.43	51.62	454383	516344
leadfinish	non noble metal	tin	7440-31-5	1.352	1.17	1.17	11669	11669
plating	noble metal	silver	7440-22-4	0.220	0.19	0.19	1903	1903
solder	non noble metal	tin	7440-31-5	0.024	0.02		207	
	noble metal	silver	7440-22-4	0.030	0.03		259	
	non noble metal	lead	7439-92-1	1.145	0.99	1.04	9881	10347
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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